

规格书编号

SPEC NO :

# 产品规格书

# SPECIFICATION

CUSTOMER 客户: \_\_\_\_\_  
PRODUCT 产品: \_\_\_\_\_ SAW FILTER \_\_\_\_\_  
MODEL NO 型号: \_\_\_\_\_ HDF911-F11 \_\_\_\_\_  
PREPARED 编制: \_\_\_\_\_ CHECKED 审核: \_\_\_\_\_  
APPROVED 批准: \_\_\_\_\_ DATE 日期: \_\_\_\_\_ 2011-2-16 \_\_\_\_\_

客户确认 CUSTOMER RECEIVED:		
审核 CHECKED	批准 APPROVED	日期 DATE

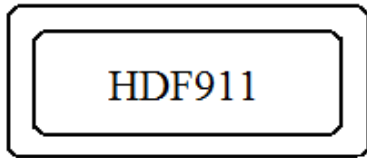
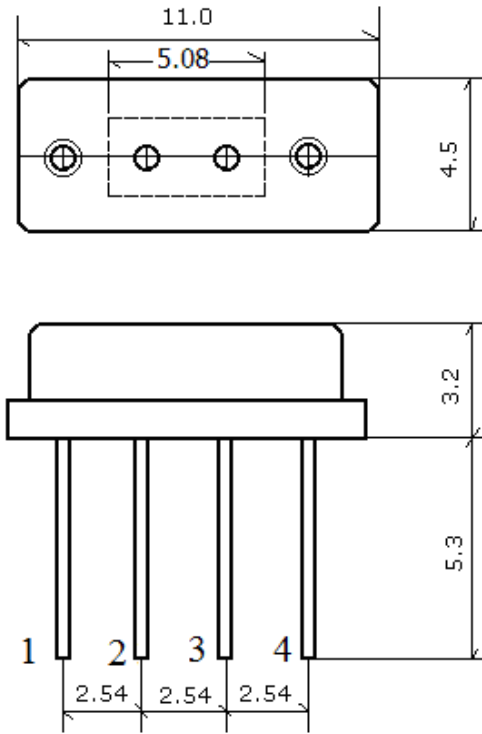
无锡市好达电子有限公司  
Shoulder Electronics Limited

更改历史记录  
History Record

更改日期 Date	规格书编号 Spec. No.	产品型号 Part No.	客户产品型号 Customer No.	更改内容描述 Modify Content	备注 Remark

**1. Package Dimension**

Unit:mm



**Pin configuration**

- 1. Input
- 4. Output
- 2,3 Ground

**2. Marking HD F911**

**3. Performance**

3.1 Application

Low-Loss SAW Filter of cordless system.  
Center Frequency:911.5MHz

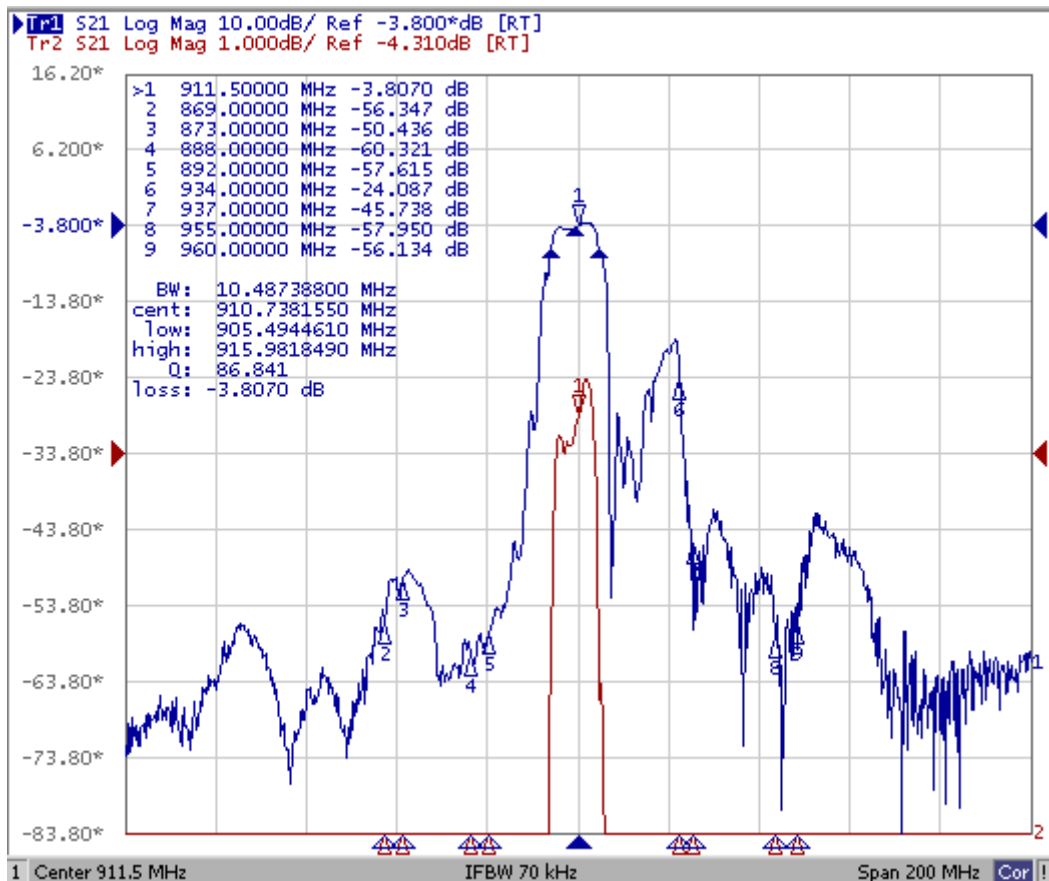
3.2 Maximum Rating

Operation Temperature Range	-40°C to +85°C
Storage Temperature Range	-40°C to +85°C
DC. Permissive Voltage	0 V DC. max.
Maximum Input Power	5dBm

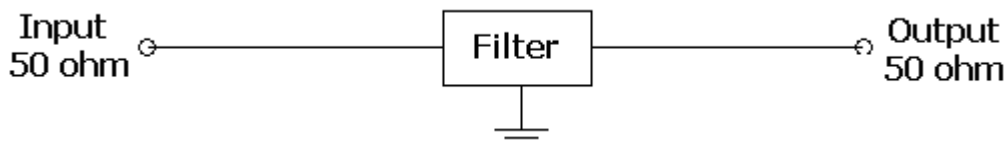
### 3.3 Electronic Characteristics

Item	Specification
Center Frequency(fo)	911.5MHz
Insertion Loss(dB)	
1.)911.5 MHz	4.5 max
2.)869-873 MHz	40 min
3.)888-892 MHz	35 min
4.)934-937 MHz	20 min
5.)955-960 MHz	40 min
6.)900 MHz	20 min.
Ripple deviation (907-916MHz)(dB)	1.5max
Input/output Impedance(Nominal)	50Ω

### 3.4 Frequency Characteristics



### 3.5 Test Circuit



## **4. ENVIRONMENTAL CHARACTERISTICS**

### 4-1 High temperature exposure

Subject the device to +85°C for 16 hours. Then release the filter into the room conditions for 24 hours prior to the measurement. It shall fulfill the specifications in 3.3.

### 4-2 Low temperature exposure

Subject the device to -40°C for 16 hours. Then release the device into the room conditions for 24 hours prior to the measurement. It shall fulfill the specifications in 3.3.

### 4-3 Temperature cycling

Subject the device to a low temperature of -40°C for 30 minutes. Following by a high temperature of +85°C for 30 Minutes. Then release the device into the room conditions for 24 hours prior to the measurement. It shall meet the specifications in 3.3.

### 4-4 Resistance to solder heat

Dip the device terminals no closer than 1.5mm into the solder bath at 260°C  $\pm$ 10°C for 10 $\pm$ 1 sec. Then release the device into the room conditions for 4 hours. The device shall meet the specifications in 3.3.

### 4-5 Solderability

Subject the device terminals into the solder bath at 245°C  $\pm$ 5°C for 5s, More than 95% area of the terminals must be covered with new solder. It shall meet the specifications in 3.3.

### 4-6 Mechanical shock

Drop the device randomly onto the concrete floor from the height of 1m 3 times. the device shall fulfill the specifications in 3.3.

### 4-7 Vibration

Subject the device to the vibration for 1 hour each in x,y and z axes with the amplitude of 1.5 mm at 10 to 55 Hz. The device shall fulfill the specifications in 3.3.

## **5. REMARK**

### 5.1 Static voltage

Static voltage between signal load & ground may cause deterioration & destruction of the component. Please avoid static voltage.

### 5.2 Ultrasonic cleaning

Ultrasonic vibration may cause deterioration & destruction of the component. Please avoid ultrasonic cleaning

### 5.3 Soldering

Only leads of component may be soldered. Please avoid soldering another part of component.